

WLCSP25_5X5

wafer level chip-size package; 25 bumps; 0.4 mm pitch; 2 x 2 x 0.5 mm body

7 June 2017

Package information

1. Package summary

Terminal position code B (bottom) Package type descriptive code **WLCSP** WLCSP25 Package type industry code

Package style descriptive code UC (uncased chip)

Package body material type X (other)

Mounting method type S (surface mount)

Issue date 11-2-2010 Manufacturer package code WLCSP25

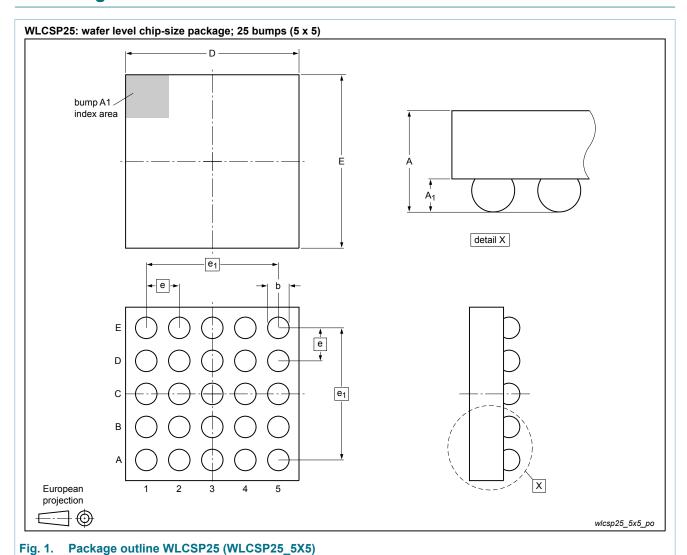
Table 1. Package summary

Symbol	Parameter	Min	Тур	Nom	Max	Unit
D	package length	2.01	-	2.05	2.09	mm
E	package width	2.01	-	2.05	2.09	mm
Α	seated height	0.47	-	0.51	0.55	mm
A ₂	package height	0.03	-	0.04	0.05	mm
е	nominal pitch	-	-	0.4	-	mm
n_2	actual quantity of termination	-	-	25	-	



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2. Package outline



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3. Legal information

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4. Contents

1.	Package summary	. 1
2.	Package outline	. 2
3.	Legal information	3

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